PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Katsuyoshi Hamano	03/08/2012
Yasutoshi Tsubota	03/08/2012
Masayuki Tomita	03/08/2012
Teruo Yoshino	03/08/2012

RECEIVING PARTY DATA

Name:	Hitachi Kokusai Electric Inc.
Street Address:	14-1, Sotokanda 4-chome
Internal Address:	Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	1018980

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13409783

CORRESPONDENCE DATA

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 215-568-6400

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US

Mail.

Correspondent Name: Volpe and Koenig, P.C. Address Line 1: 30 South 17th Street

Address Line 2: United Plaza

Address Line 4: Philadelphia, PENNSYLVANIA 19103

ATTORNEY DOCKET NUMBER:	HITACHI10-21010043US01
NAME OF SUBMITTER:	Daniel N. Calder

Total Attachments: 1

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PATENT

134097

CH \$40.00

REEL: 028224 FRAME: 0452

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi Kokusai Electric Inc., a corporation organized under the laws of Japan,

located at 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo, Japan,

receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Kokusai Electric Inc., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SUBSTRATE PROCESSING APPARATUS AND A METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi Kokusai Electric Inc.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Kokusai Electric Inc.

Signed on the date(s) indicated aside our signatures:

RECORDED: 05/17/2012

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Katsuyoshi HAMANO</u> Katsuyoshi HAMANO	3/8/2012
Yasutoshi Tsubota Yasutoshi TSUBOTA	3/8/20/2
Masayuki Tomita Masayuki TOMITA	3/8/20/2
4) Jeruo, Joshino Teruo YOSHINO	3/8/20/2

PATENT REEL: 028224 FRAME: 0453